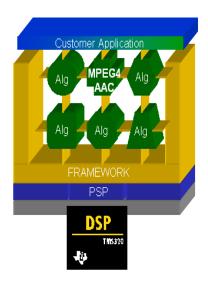


- eXpressDSP™ compliant
- Supports sampling frequency conversion from any to any frequency within the standard set (8, 11.025, 16, 22.05, 24, 32, 44.1, 48) KHz



Description:

- Efficient Stereo SRC implementation on a single TMS320C55x DSP
- Required memory for code and data is 2.6Kw. This makes it capable run on the internal memory of C55x processors.
- Supported Sampling Frequencies (KHz): 8, 11.025, 12, 16, 22.05, 24, 32, 44.1, 48
- 16th Order Lagrange Interpolation for upward conversion
- 2nd Order Lowpass Elliptic Filter to reduce aliasing
- 16th Order Lagrange Interpolation for downward conversionm
- TI eXpressDSP compliant
- CCS version 2.0 with CG Tools version 2.0 and Skywalker board with DA250(C5509 core) are used for development.



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Summary of Performance

Table 1. **Configuration Table**

CONFIGURATION	ID
For Sampling Rate Conversion from 44.1KHz to 48.0KHz	А

Table 2. Cycles Information-Profiled on TMS320DA250 EVM

CONFIGURATION ID	TEST FILE PARAMETERS	PERFORMANCE STATISTICS (IN MIPS)		
		AVERAGE	PEAK	
А	Sampling Frequency 44.1 KHz	6.352	7.062	

Table 3. Memory Statistics- Generated with Code Generation Tools Version 2.55

	MEMORY STATISTICS ¹				
CONFIGURATION ID	PROGRAM DATA MEMORY		TOTAL		
	MEMORY	INTERNAL	EXTERNAL	STACK	TOTAL
A	3.864	2.929	0	0.500	7.293

All memory requirements are expressed in kilobytes (1 kilobyte = 1024 8-bit bytes).

Table 4. **Internal Data Memory Split-up**

	DATA MEMORY – INTERNAL ²		
CONFIGURATION ID	SHARED		INSTANCE ¹
	CONSTANTS	SCRATCH	INSTANCE
Α	2.343	0	0.586

All memory requirements are expressed in kilobytes (1 kilobyte = 1024 8-bit bytes)

Does not include I/O Buffers

Notes

- I/O Buffers Input Buffer Size = 1024 bytes,
 Output Buffer Size = 128 bytes.
- Total Data Memory for N Non-Pre-Emptive Instances =
 Constants + Runtime Tables + Scratch + N*(Instance + I/O buffers + Stack)
- Total Data Memory for N Pre-Emptive Instances =
 Constants + Runtime Tables + N*(Instance + I/O buffers + Stack + Scratch)
- Stack includes stack and sysstack



SAMPLE RATE CONVERTER ON TMS320DA250

RELEASE VERSION V3.0 – 28 MAY 2003

glossary

Constants Elements that go into .const memory section

Scratch Memory space that can be reused across different instances of the algorithm

Shared Sum of Constants and Scratch

Instance Persistent-Memory that contains persistent information - allocated for each

instance of the algorithm

Acronyms

SRC : Sample Rate Converter



REVISION HISTORY

This data sheet revision history highlights the technical changes made to the SPRA237A data sheet to make it an SPRA237B revision.

Scope: Applicable updates to SRC on TMS320DA250 have been incorporated.

DATE	VERSION	ADDITIONS/CHANGES/DELETIONS
22 ND May 03	v1.0	Initial
28 TH May 03	v1.1	Review Comments Incorporated

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